and B is in each case a group of the formula:

wherein R^1 , R^2 and R^3 each, independent of one another, are hydrogen or a bond to a group B with the proviso that each group A has either one or two bonds to group B; (i) R^4 and R^4 , and (ii) R^5 and R^5 each, independent of one another, are either together a direct bond or are hydrogen and a bond to a group A, with the proviso that each group B has either one or two bonds to group A; the indices m and n are 0 or 1 and x is an integer from 0 to 10, with the proviso that at least one of the numbers m, n and x is other than 0 and x and x are not both at the same time 1, and mixtures thereof with one another and/or with those compounds of formula I in which x and x deviate from the above definitions by both being 1.

- 7. The at least one oligophenol cyanate according to Claim 6, wherein x is from 0 to 5.
- 8. A process for preparing the at least one oligophenol cyanate according to Claim 6, comprising reacting at least one oligophenol of the formula:

$$[A'-]_n[B-A'-]_xB[-A']_m$$

in which A' is a group of the formula:



and B, R^1 , R^2 , R^3 , R^4 , R^5 , R^5 , R^5 , m, n and x are as previously defined with cyanogen chloride in the presence of a tertiary amine.

- 9. A process of preparing a fiber-reinforced composite, comprising: admixing fibers and the at least one unsaturated oligophenol cyanate according to Claim 6; and polymerizing the at least one unsaturated oligophenol cyanate to a polytriazine resin which is matrix material in the resultant fiber-reinforced composite.
- 10. The fiber-reinforced composite prepared by the process according to Claim 9.
- 11. A process of preparing a radiation-curable lacquer, comprising admixing the at least one unsaturated oligophenol cyanate according to Claim 6 and other components of a lacquer whereby the radiation-curable lacquer is provided.
- 12. The radiation-curable lacquer prepared by the process according to Claim 11.
- 13. A process comprising applying the radiation-curable lacquer according to Claim 12 to a substrate and radiation-curing the radiation-curable lacquer.
- 14. A process of preparing a radiation-curable varnish comprising admixing the at least one unsaturated oligophenol cyanate according to Claim 6 and other components of a varnish whereby the radiation-curable varnish is obtained.
- 15. The process according to Claim 14, wherein the other components of the varnish are other components of a lithographic varnish and the radiation-curable varnish is a radiation curable lithographic varnish.
- 16. The radiation-curable varnish prepared by the process according to Claim 14.
- 17. The radiation-curable lithographic varnish prepared by the process according to Claim 15.

- 18. A process comprising applying the radiation-curable varnish according to Claim 16 to a substrate and radiation-curing the radiation-curable varnish.
- 19. A process of preparing a radiation-curable solder resist for a circuit board, comprising admixing the at least one unsaturated oligophenol cyanate according to Claim 6 and other components of a solder resist for a circuit board.
- 20. The radiation-curable solder resist for a circuit board prepared according to Claim 19.

In The Specification

In accordance with 37 C.F.R. 1.1121, please substitute for the original paragraph on page 2, lines 21 to 25, the following rewritten version of the paragraph on page 2, lines 21 to 25, as amended. The changes made are shown explicitly in the attached "Version With Markings To Show Changes Made".

Please substitute for the original paragraph on page 2, lines 21 to 25, the following rewritten version of the paragraph on page 2, lines 21 to 25, as amended:

In accordance with the invention this object is achieved by the unsaturated oligophenol cyanates of the formula I in accordance with the invention. The molecule of these compounds has at least one olefinic double bond (R^4-R^4 ' and/or R^5-R^5 ' according to formula I) which permits free-radical addition polymerization.

In the Abstract:

Please cancel the original Abstract and insert therefor the new abstract submitted on the separate page attached hereto.